

## **Rochester Electronics Manufactured Components**

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

# **Quality Overview**

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
  - Class Q Military
  - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)

• Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing. National Semiconductor

### MM54HC374/MM74HC374 TRI-STATE® Octal D-Type Flip-Flop

#### **General Description**

**Connection Diagram** 

These high speed Octal D-Type Flip-Flops utilize advanced silicon-gate CMOS technology. They possess the high noise immunity and low power consumption of standard CMOS integrated circuits, as well as the ability to drive 15 LS-TTL loads. Due to the large output drive capability and the TRI-STATE feature, these devices are ideally suited for interfacing with bus lines in a bus organized system.

These devices are positive edge triggered flip-flops. Data at the D inputs, meeting the setup and hold time requirements, are transferred to the Q outputs on positive going transitions of the CLOCK (CK) input. When a high logic level is applied to the OUTPUT CONTROL (OC) input, all outputs go to a high impedance state, regardless of what signals are present at the other inputs and the state of the storage elements. The 54HC/74HC logic family is speed, function, and pinout compatible with the standard 54LS/74LS logic family. All inputs are protected from damage due to static discharge by internal diode clamps to  $V_{CC}$  and ground.

#### Features

- Typical propagation delay: 20 ns
- Wide operating voltage range: 2-6V
- Low input current: 1 µA maximum
- Low quiescent current: 80 µA maximum
- Compatible with bus-oriented systems
- Output drive capability: 15 LS-TTL loads

#### **Dual-In-Line Package** CLOCK 7Q 5D 5Q 7D 6Q Vcc 8Q 8D 12 11 20 15 13 19 10 n n 0 0 D D n CK СК Q Q OE cκ CK CI Q Q 10 OUTPUT 10 1D 2D 20 30 3D 4D 4Q GND CONTROL TI /F/5336-1 **Top View** Order Number MM54HC374 or MM74HC374 **Truth Table** H = high Level, L = Low Level Output Clock Data Output X = don't Care Control $\uparrow$ = transition from low-to-high L 1 н н Z = high impedance state $Q_0$ = the level of the output before steady state L 1 L L input conditions were established L L Х Q<sub>0</sub>

TRI-STATE® is a registered trademark of National Semiconductor Corp

Н

Х

х

Ζ

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#### Absolute Maximum Ratings (Notes 1 & 2)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications. Supply Voltage (V<sub>CC</sub>)

-0.5 to +7.0V

 $\pm$  20 mA

 $\pm$  35 mA

 $\pm$  70 mA

600 mW

500 mW

260°C

-1.5 to  $V_{CC}\!+\!1.5V$ 

-0.5 to  $V_{CC}\!+\!0.5V$ 

-65°C to +150°C

### **Operating Conditions**

Supply Voltage (V <sub>CC</sub> )	Min 2	Max 6	Units V
DC Input or Output Voltage (V <sub>IN</sub> , V <sub>OUT</sub> )	0	$V_{CC}$	V
Operating Temp. Range $(T_{A})$			
MM74HC	-40	+85	°C
MM54HC	-55	+125	°C
Input Rise or Fall Times			
$(t_r, t_f) V_{CC} = 2.0V$		1000	ns
V <sub>CC</sub> =4.5V		500	ns
$V_{CC} = 6.0V$		400	ns

### **DC Electrical Characteristics**

DC Input Voltage (VIN)

Power Dissipation (P<sub>D</sub>)

S.O. Package only

(Note 3)

DC Output Voltage (V<sub>OUT</sub>)

Clamp Diode Current (I<sub>IK</sub>, I<sub>OK</sub>)

DC Output Current, per pin (I<sub>OUT</sub>)

DC V<sub>CC</sub> or GND Current, per pin (I<sub>CC</sub>)

Storage Temperature Range (T<sub>STG</sub>)

Lead Temp. (TL) (Soldering 10 seconds)

Symbol	Parameter	Conditions	v <sub>cc</sub>	T <sub>A</sub> =25°C		74HC T <sub>A</sub> = - 40 to 85°C	54HC T <sub>A</sub> = - 55 to 125°C	Units
				Тур	Typ Guaranteed Limits			
V <sub>IH</sub>	Minimum High Level Input Voltage		2.0V 4.5V 6.0V		1.5 3.15 4.2	1.5 3.15 4.2	1.5 3.15 4.2	v v v
V <sub>IL</sub>	Maximum Low Level Input Voltage**		2.0V 4.5V 6.0V		0.5 1.35 1.8	0.5 1.35 1.8	0.5 1.35 1.8	V V V
0.11	Minimum High Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \ \mu A$	2.0V 4.5V 6.0V	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 6.0 \text{ mA}$ $ I_{OUT}  \le 7.8 \text{ mA}$	4.5V 6.0V	4.2 5.7	3.98 5.48	3.84 5.34	3.7 5.2	V V
I UL	Maximum Low Level Output Voltage	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 20 \ \mu A$	2.0V 4.5V 6.0V	0 0 0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V V V
		$V_{IN} = V_{IH} \text{ or } V_{IL}$ $ I_{OUT}  \le 6.0 \text{ mA}$ $ I_{OUT}  \le 7.8 \text{ mA}$	4.5V 6.0V	0.2 0.2	0.26 0.26	0.33 0.33	0.4 0.4	V V
I <sub>IN</sub>	Maximum Input Current	$V_{IN} = V_{CC}$ or GND	6.0V		±0.1	±1.0	±1.0	μA
I <sub>OZ</sub>	Maximum TRI-STATE Output Leakage Current	$V_{IN} = V_{IH}, OC = V_{IH}$ $V_{OUT} = V_{CC} \text{ or GND}$	6.0V		±0.5	±5	±10	μΑ
ICC	Maximum Quiescent Supply Current	V <sub>IN</sub> =V <sub>CC</sub> or GND I <sub>OUT</sub> =0 μA	6.0V		8.0	80	160	μΑ

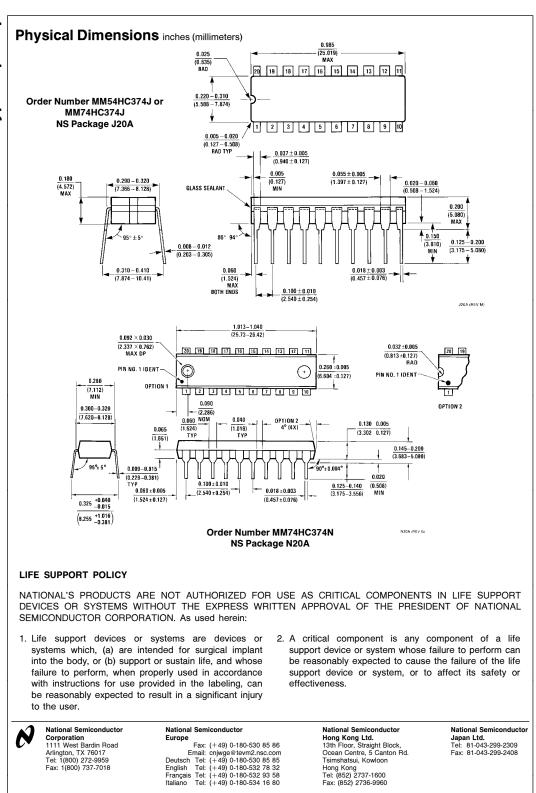
Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground.

Note 4: For a power supply of 5V  $\pm$  10% the worst case output voltages (V<sub>OH</sub>, and V<sub>OL</sub>) occur for HC at 4.5V. Thus the 4.5V values should be used when designing with this supply. Worst case  $V_{IH}$  and  $V_{IL}$  occur at  $V_{CC}$ =5.5V and 4.5V respectively. (The  $V_{IH}$  value at 5.5V is 3.85V.) The worst case leakage current ( $I_{IN}$ ,  $I_{CC}$ , and  $I_{OZ}$ ) occur for CMOS at the higher voltage and so the 6.0V values should be used.

\*\*VIL limits are currently tested at 20% of V<sub>CC</sub>. The above VIL specification (30% of V<sub>CC</sub>) will be implemented no later than Q1, CY'89.

Symbo	Parameter	Conditions	Тур	,   <sup>G</sup>	uarante Limit	ed Units		
f <sub>MAX</sub>	Maximum Operating Frequency		50		35	MHz		
t <sub>PHL</sub> , t <sub>PI</sub>		C <sub>L</sub> =45 pF	20		32	ns		
t <sub>PZH</sub> , t <sub>P</sub>	ZL Maximum Output Enable Time	$R_{L} = k\Omega$ $C_{L} = 45 \text{ pF}$	19		28	ns		
t <sub>PHZ</sub> , t <sub>P</sub>	LZ Maximum Output Disable Time	$\begin{array}{c} R_{L} = k\Omega\\ C_{L} = 5pF \end{array}$	17		25	ns		
ts	Minimum Setup Time				20	ns		
t <sub>H</sub>	Minimum Hold Time				5	ns		
t <sub>W</sub>	Minimum Pulse Width		9		16	ns		
AC El	ectrical Characteris	stics v <sub>cc</sub> =2	2.0-6.0	√, C <sub>L</sub> =	50 pF, t	<sub>r</sub> =t <sub>f</sub> =6 ns (unles	s otherwise specified)	
Symbol	Parameter	Conditions	v <sub>cc</sub>		= 25°C	74HC T <sub>A</sub> = -40 to 85		Unit
				Тур	_		eed Limits	
ЛАХ	Maximum Operating Frequency	C <sub>L</sub> =50 pF	2.0V 4.5V 6.0V		6 30 35	5 24 28	4 20 23	MH: MH: MH:
PHL, t <sub>PLH</sub>	Maximum Propagation Delay, Clock to Q	$C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	2.0V 2.0V	68 110	180 230	225 288	270 345	ns ns
		$C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	4.5V 4.5V	22 30	36 46	45 57	48 69	ns ns
		$C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	6.0V 6.0V	20 28	31 40	39 50	46 60	ns ns
<sub>ZH</sub> , t <sub>PZL</sub>	Maximum Output Enable	$R_L = 1 k\Omega$						
	Time	$C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	2.0V 2.0V	50 80	150 200	189 250	225 300	ns ns
		$C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	4.5V 4.5V	21 30	30 40	37 50	45 60	ns ns
		$C_L = 50 \text{ pF}$ $C_L = 150 \text{ pF}$	6.0V 6.0V	19 26	26 35	31 44	39 53	ns ns
PHZ, <sup>t</sup> PLZ	Maximum Output Disable Time	$R_L = 1 k\Omega$ $C_L = 50 pF$	2.0V 4.5V 6.0V	50 21 19	150 30 26	189 37 31	225 45 39	ns ns ns
3	Minimum Setup Time		2.0V 4.5V 6.0V		50 9 9	60 13 11	75 15 13	ns ns
1	Minimum Hold Time		2.0V 4.5V		5 5	30 5	555	ns ns ns
	Minimum Data 147 IV		6.0V	00	5	5	5	ns
V	Minimum Pulse Width		2.0V 4.5V 6.0V	30 9 8	80 16 14	100 20 18	120 24 20	ns ns ns
HL, <sup>t</sup> TLH	Maximum Output Rise and Fall Time	$C_L = 50 \text{ pF}$	2.0V 4.5V	25 7	60 12	75 15	90 18	ns ns
, t <sub>f</sub>	Maximum Input Rise and Fall Time, Clock		6.0V 2.0V 4.5V	6	10 1000 500	13 1000 500	15 1000 500	ns ns ns
PD	Power Dissipation	(per flip-flop)	6.0V		400	400	400	ns
FU	Capacitance (Note 5)	$OC = V_{CC}$ OC = GND		30 50				pF pF
IN Note 5: Coo	Maximum Input Capacitance	consumption D	Cop V- 2	5	10	10	10	pF
Note 5: C <sub>PD</sub>	determines the no load dynamic power	consumption, P <sub>D</sub> =	C <sub>PD</sub> V <sub>CC<sup>2</sup></sub>	f+lcc	/ <sub>CC</sub> , and th	ne no load dynamic cu	irrent consumption, $I_S = C_{PD} V_{CC}$	f+I <sub>CC</sub> .



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